

Multilayer Ceramic Chip Capacitors



Kyocera Ceramic Chip Capacitors are available for different applications as classified below:

Series	Dielectric Options	Typical Applications	Features	Terminations	Available Size
СМ	C0G (NP0) X5R X7R *X6S *X7S Y5V	General purpose	Wide cap range	Nickel barrier	01005, 0201, 0402 0603, 0805, 1206 1210, 1812
ст	X5R X7R Y5V	IC card (Decoupling)	Low profile	Nickel barrier	0201, 0402, 0603 0805, 1206, 1210
CA	C0G (NP0) X5R, X7R	Digital signal Pass line	Reduction in placing cost	Nickel barrier	0405, 0508
CL	X7S	ICs (Decoupling)	Low inductance	Nickel barrier	0204, 0306
CF	C0G (NP0) X7R	High voltage & Power circuits	High voltage 250VDC, 630VDC 1000VDC, 2000VDC 3000VDC, 4000VDC	Nickel barrier	0805, 1206, 1210 1812, 2208, 1808 2220
DM	X7R	Automotive	Thermal shock Resistivity High reliability	Nickel barrier	0603,0805,1206

^{*} Option

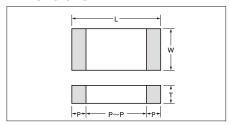
^{*} Negative temperature coefficient dielectric types are available on request.



Multilayer Ceramic Chip Capacitors



Dimensions



Dimensions and Packaging Quantities

Size	Co		Dimension			Dimensions (m					antity per reel
3120	JIS	EIA	Code	L	W	Т	P min.	P max.	P to P min.	∮180 Reel	∮330 Reel
02	0402	01005	Α	0.4±0.02	0.2±0.02	0.2±0.02	0.07	0.14	0.13	40kp (E4/1)	_
										20kp (P8/2) 30kp (P8/1)	_
			Α	0.010.00	0.010.00	0.22 max.	0.40	0.00	0.00	15kp (P8/2)	50kp (P8/2)
03	0603	0201	В	0.6±0.03	0.3±0.03	0.3±0.03	0.10	0.20	0.20	30kp (P8/1)	50kp (P8/2)
03	0003	0201	В			0.5±0.05				15kp (P8/2)	30KP (F6/2)
			С	0.6±0.05	0.3±0.05	0.3±0.05	0.13	0.23	0.19	30kp (P8/1) 15kp (P8/2)	50kp (P8/2)
						0.05				20kp (P8/1)	FOL (DO (O)
			Α			0.25 max.				10kp (P8/2)	50kp (P8/2)
			В	1.0±0.05	0.5±0.05	0.35 max.				20kp (P8/1)	50kp (P8/2)
			_				-			10kp (P8/2) 20kp (P8/1)	
05	1005	0402	С			0.5±0.05	0.15	0.25	0.30	10kp (P8/2)	50kp (P8/2)
US	1005	0402	D			0.35 max.	0.13	0.35	0.30	20kp (P8/1)	50kp (P8/2)
				1.0±0.10	0.5±0.10	oloo maxi	_			10kp (P8/2) 20kp (P8/1)	00.15 (1.072)
			E			0.5±0.10				10kp (P8/2)	50kp (P8/2)
			E	F 1.0±0.15 0.5±0.15 0.5±0.15				20kp (P8/1)	50kp (P8/2)		
				1.0±0.15	0.0±0.10					10kp (P8/2)	,
			A	1.6±0.10	0.8±0.10	0.55 max.	-		-	4kp (P8/4) 8kp (P8/2)	10kp (P8/4) 20kp (P8/2)
			В	1.0±0.10	0.0±0.10	0.8±0.10				4kp (P8/4)	10kp (P8/4)
			С			0.55 max.				8kp (P8/2)	20kp (P8/2)
105	1608	0603		1.6±0.15	0.8±0.15	0.00 max.	0.20	0.60	0.50	4kp (P8/4)	10kp (P8/4)
			D			0.8±0.15				8kp (P8/2) 4kp (P8/4)	20kp (P8/2) 10kp (P8/4)
			-			0 FF may				8kp (P8/2)	20kp (P8/2)
			E	1.6±0.2	0.8±0.2	0.55 max.				4kp (P8/4)	10kp (P8/4)
			F A			0.8±0.2 0.55 max.				* 4kp (P8/4)	10kp (P8/4)
			B			0.95 max.	-			4kp (P8/4)	10kp (P8/4)
			С			1.00 max.				4kp (E8/4)	10kp (E8/4)
			D	2.0±0.10	1.25±0.10 1.25±0.15	0.6±0.10	-			4kp (P8/4)	10kp (P8/4)
			E F			0.85±0.10 1.05±0.10	_			4kp (P8/4) 3kp (E8/4)	10kp (P8/4) 10kp (E8/4)
21	2012	0805	G			1.25±0.10	0.20	0.75	0.70	3kp (E8/4)	10kp (E8/4)
			Н			0.55 max.				4kp (P8/4)	10kp (P8/4)
			J	2.0±0.15		0.95 max.				4kp (P8/4)	10kp (P8/4)
			K L			1.25±0.15 0.95 max.				3kp (E8/4) 4kp (P8/4)	10kp (E8/4) 10kp (P8/4)
			M	2.0±0.20	1.25±0.20	1.25±0.20				3kp (E8/4)	10kp (E8/4)
			Α			0.85±0.10				4kp (P8/4)	10kp (P8/4)
			B C			0.95 max. 1.00 max.				4kp (P8/4) 4kp (E8/4)	10kp (P8/4) 10kp (E8/4)
			D	3.2±0.20	1.6±0.15	1.15±0.10	-			3kp (E8/4)	10kp (E8/4)
316	3216	1206	E			1.25±0.10	0.30	0.85	1.40	3kp (E8/4)	10kp (E8/4)
			F			1.6±0.15				2.5kp (E8/4)	5kp (E8/4)
			G H	3.2±0.20	1.6±0.20	0.95 max. 1.00 max.				4kp (P8/4) 4kp (E8/4)	10kp (P8/4) 10kp (E8/4)
			J	0.2=0.20	1.020.20	1.6±0.20				2.5kp (E8/4)	5kp (E8/4)
			Α			1.00 max.				4kp (E8/4)	10kp (E8/4)
			B C			1.40 max.				3kp (E8/4)	10kp (E8/4)
32	3225	1210	D	3.2±0.20	2.5±0.20	1.60 max. 1.6±0.15	0.30	1.00	1.40	2.5kp (E8/4) 2.5kp (E8/4)	5kp (E8/4) 5kp (E8/4)
-	OLLO	12.10	Ē	0.2=0.20	2.0=0.20	2.20 max.	0.00	1.00	10	2kp (E8/4)	5kp (E8/4)
			F			2.0±0.2				2kp (E8/4)	5kp (E8/4)
			G			2.5±0.2				1kp (E8/4) 2kp (E12/4)	4kp (E8/4)
42	4520	1808	A B	4.5±0.20	2.0±0.20	1.6 max. 2.2 max.	0.15	0.85	2.60	2kp (E12/4) 2kp (E12/4)	
			Α			2.0 max.				1kp (E12/8)	_
			В			2.0±0.2	_			1kp (E12/8)	-
43	4532	1812	D D	4.5±0.30	3.2±0.20	2.5 max. 2.5±0.2	0.30	1.10	2.00	0.5kp (E12/8) 0.5kp (E12/8)	
			E			2.5±0.2 2.8 max.	1			0.5kp (E12/8)	_
			F			2.8±0.2				0.5kp (E12/8)	_
52	5720	2208	A	5.7±0.40	2.0±0.20	2.2 max.	0.15	0.85	4.20	2kp (12/8)	_
			<u>A</u>	F 710 40	5.0±0.40	2.0 max. 2.5 max.	0.30	1.40	2.50	1kp (E12/8) 0.5kp (E12/8)	
55	5750	2220	В	5.7±0.40							

Note: Taping denotes the quantity packaged per reel (kp means 1000 pieces).

^{*} Please contact us.





KYOCERA PART NUMBER CM 21 X7R 104 K 50 Α SERIES CODE -CM = General Purpose CL **ICs** High Voltage CF = CT = Low Profile DM = CA = Arrays Automotive SIZE CODE -SIZE EIA (JIS) SIZE EIA (JIS) SIZE EIA (JIS) 02 = 01005 (0402)32 = 1210 (3225) D11 = 0405 (1014)/2 cap03 = 0201 (0603)42 = 1808 (4520) F12 = 0508 (1220)/4 cap05 = 0402 (1005)43 = 1812 (4532) 52 = 2208 (5720) 105 = 0603 (1608)21 = 0805 (2012)55 = 2220 (5750) 316 = 1206 (3216)**DIELECTRIC CODE** -**CODE EIA CODE** CG = C0G (NPO)X7S = X7S (Option) X5R = X5RX6S = X6S (Option) X7R = X7RY5V = Y5VNegative temperature coefficient dielectric types are available on request. CAPACITANCE CODE -Capacitance expressed in pF. Two significant digits plus number of zeros. For Values < 10pF, Letter R denotes decimal point, 100000pF = 1041.5pF = 1R5 $0.1\mu F = 104$ 0.5pF = R50100μF 4700pF = 472= 107 TOLERANCE CODE — $A = \pm 0.05pF$ (option) $D = \pm 0.5pF$ $J = \pm 5\%$ Z = -20 to +80% $B = \pm 0.1pF$ $F = \pm 1pF$ $K = \pm 10\%$ $G = \pm 2\%$ (option) $M = \pm 20\%$ $C = \pm 0.25 pF$ **VOLTAGE CODE** -04 = 4VDC100 = 100VDC1000 = 1000VDC250 = 250VDC2000 = 2000VDC 06 = 6.3VDC10 = 10VDC400 = 400VDC3000 = 3000VDC4000 = 4000VDC16 = 16VDC630 = 630VDC25 = 25VDC35 = 35VDC50 = 50VDCTERMINATION CODE -A = Nickel Barrier/Tin K = Nickel Barrier/ Au PACKAGING CODE -B = BulkL = 13" Reel Taping & 4mm Cavity pitch C = Bulk Cassette (option) H = 7" Reel Taping & 2mm Cavity pitch T = 7" Reel Taping & 4mm Cavity pitch N = 13" Reel Taping & 2mm Cavity pitch *P = 7" Reel Taping & 1mm Cavity pitch Q = 7" Reel Taping & 1mm Cavity pitch * Carrier tape width 4mm.

OPTION

Thickness max. value is indicated in CT series

EX. 125 \rightarrow 1.25mm max. 095 \rightarrow 0.95mm max.



Multilayer Ceramic Chip Capacitors Temperature Characteristics and Tolerance



Temperature Compensation Type

Dielectric Value (pF)	C0G (NPO) 0 ppm/ °C	U∆ (N750) -750 ppm/ °C	SL +350 to -1000ppm/ °C
0.5 to 2.7	CK	UK	SL
3.0 to 3.9	CJ	UJ	SL
4.0 to 9.0	СН	UJ	SL
≥10	CG	UJ	SL

K = ± 250 ppm/ °C, J = ± 120 ppm/ °C, H = ± 60 ppm/ °C, G = ± 30 ppm/ °C e.g. $CG = 0\pm30$ ppm/ $^{\circ}C$

Note: All parts of COG will be marked as "CG" but will conform to the above table.

High Dielectric Constant Type

EIA Dielectric	Temperature Range	∆C max.			
X5R	−55 to 85°C	±15%			
X7R	–55 to 125°C	±1370			
*X7S	−55 to 125°C	±22%			
*X6S	−55 to 105°C	±22%			
Y5V	−30 to 85°C	-82 to +22%			

^{*} option

Available Tolerances

Dielectric materials, capacitance values and tolerances are available in the following combinations only:

EIA Dielectric	Tolerance	Capacitance			
	C=±0.25pF	*1 <10pF			
	D=±0.50pF	< TUPF			
	*3 A=±0.05pF	<0.5pF			
COG	B=±0.1pF	≤5pF			
	*3 G=±2%	\10-F			
	J=±5%	≥10pF			
	K=±10%	E12 Series			
*3 X6S X5R	*2 K=±10%	*4 E3 Series			
*3 X7S X7R	M=±20%	E3 Series			
Y5V	Z=-20% to +80%	E3 Series			

E Standard Number

E3	E 6	E12	E24 (C	ption)
	1.0	1.0	1.0	1.1
1.0	1.0	1.2	1.2	1.3
1.0	1.5	1.5	1.5	1.6
	1.5	1.8	1.8	2.0
	2.2	2.2	2.2	2.4
2.2	2.2	2.7	2.7	3.0
2.2	3.3	3.3	3.3	3.6
	3.3	3.9	3.9	4.3
	4.7	4.7	4.7	5.1
4.7	4.7	5.6	5.6	6.2
4.7	6.8	6.8	6.8	7.5
	0.0	8.2	8.2	9.1

^{*1} Nominal values below 10pF are available in the standard values of 0.5pF, 1.0pF, 1.5pF, 2.0pF, 3.0pF, 4.0pF, 5.0pF, 6.0pF, 7.0pF, 8.0pF, 9.0pF *2 $J = \pm 5\%$ for X7R (X5R) is available on request.

^{*3} option

^{*4} E6 series is available on request.





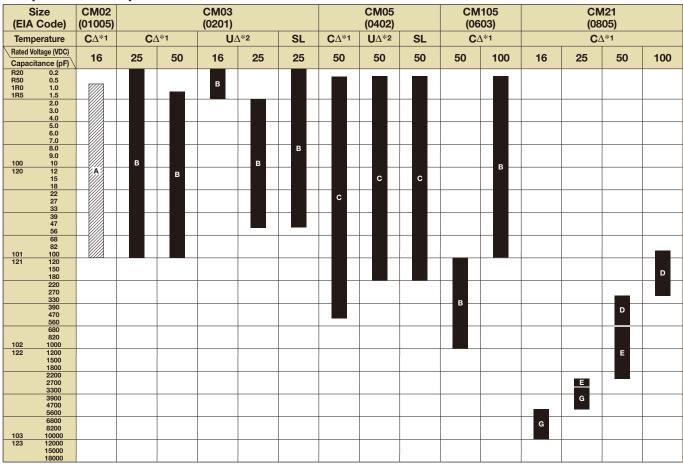
Features

We offer a diverse product line ranging from ultra–compact (0.4×0.2mm) to large (4.5×3.2mm) components configured for a variety of temperature characteristics, rated voltages, and packages. We offer the choice and flexibility for almost any applications.

Applications

This standard type is ideal for use in a wide range of applications, from commercial to industrial equipment.

Temperature Compensation Dielectric



[•] E24 sereis is available on request.

Optional Spec.

*1: CG,CH,CJ,CK

*2: UJ,UK

Alphabets in capacitance chart denote dimensions. Please refer to the below table for detail.

(Example)

In case of "B" for CM03;

L: 0.6±0.03mm W: 0.3±0.03mm T: 0.3±0.03mm

Size	Size	Dir	Dimension (mm)							
Size	Code	L	W	Т						
02	Α	0.4±0.02	0.2±0.02	0.2±0.02						
03	В	0.6±0.03	0.3±0.03	0.3±0.03						
05	С	1.0±0.05	0.5±0.05	0.5±0.05						
105	В	1.6±0.10	0.8±0.10	0.8±0.10						
	D			0.6±0.10						
21	E	2.0±0.10	1.25±0.10	0.85±0.10						
	G			1.25±0.10						





X5R Dielectric

(EIA	Size A Code)	CN (010	102 005)		CN (02	103 (01)				CN (04	105 02)					CM (06	105 03)					CN (08	121 05)		
	Voltage (VDC)	6.3	10	6.3	10	16	25	4	6.3	10	16	25	50	4	6.3	10	16	25	50	4	6.3	10	16	25	50
101	100																								
151	150 220 330		A8				В3																		
102	470 680 1000												C1												
152	1500 2200 3300	A8	<i>V///</i>			В3																			
103	4700 6800 10000	A8			B4																				
153	15000 22000 33000	V////										СЗ							В1						D1 E1
104	47000 68000 100000	A8		B7							C3							В3							G1
105	220000 470000 1000000			B8 C8	[B8]				C5 C7	C8 C8	C8					B4	вз	D8					G3	G3	G8
106	2200000 4700000 10000000							E8 F9	[C8]						D5 D8	B8 D8	B8				G5 M5	G4 M8	K8 M8	М8	
107	22000000 47000000 100000000																			М7					

Size (EIA Code)		CM316 (1206)							CN (12					143 12)
Rated Voltage (VDC) Capacitance (pF)	6.3	10	16	25	50	100	4	6.3	10	16	25	50	6.3	50
220000 470000 105 1000000				D3	D1	J3 _					В3	B1 F1		
2200000 4700000 106 10000000	F5	F4	F3	F3 J8	[J3]				F4	C3 G3	F3 G3 G8			D1
22000000 47000000 107 100000000	J5	J8	J8				G5	G5	G4	G3	G8		F5	

- E6 series is standard.
- E3 series is standard for the size 316 and larger.
 E12 series is available on request.
- Optional Spec.

Two digits alphanumerics in capacitance chart denote dimensions and tan $\delta.\,$ Please refer to the below table for detail.

(Example)

In case of "B2" for CM03; L : 0.6±0.03mm W: 0.3±0.03mm T : 0.3±0.03mm Tan δ : 3.5% max.

Size	Size	Dir	mension (m	ım)
Size	Code	L	W	Т
02	Α	0.4±0.02	0.2±0.02	0.2±0.02
03	В	0.6±0.03	0.3±0.03	0.3±0.03
03	С	0.6±0.05	0.3±0.05	0.3±0.05
	С	1.0±0.05	0.5±0.05	0.5±0.05
05	E	1.0±0.10 0.5±0.10		0.5±0.10
	F	1.0±0.15	0.5±0.15	0.5±0.15
105	В	1.6±0.10	0.8±0.10	0.8±0.10
103	D	1.6±0.15	0.8±0.15	0.8±0.15
	D	2.0±0.10	1.25±0.10	0.6±0.10
	E	2.0±0.10	1.25±0.10	0.85±0.10
21	G	2.0±0.10	1.25±0.10	1.25±0.10
	K	2.0±0.15	1.25±0.15	1.25±0.15
	М	2.0±0.20	1.25±0.20	1.25±0.20

Size	Size	Dir	nension (m	nm)
Size	Code	L	W	Т
	D	3.2±0.20	1.6±0.15	1.15±0.10
316	F	3.2±0.20	1.6±0.15	1.6±0.15
	J	3.2±0.20	1.6±0.20	1.6±0.20
	В	3.2±0.20	2.5±0.20	1.40 max.
32	С	3.2±0.20	2.5±0.20	1.60 max.
32	F	3.2±0.20	2.5±0.20	2.0±0.2
	G	3.2±0.20	2.5±0.20	2.5±0.2
43	D	4.5±0.30	3.2±0.20	2.5±0.2
43	F	4.5±0.30	3.2±0.20	2.8±0.2

$\begin{array}{c} \text{Tan } \delta \\ \text{Code} \end{array}$	Tan δ
1	2.5% max.
2	3.5% max.
3	5.0% max.
4	7.0% max.
5	7.5% max.
7	10.0% max.
8	12.5% max.
9	20.0% max.





X7R Dielectric

	Size (Code)	CM02 (01005)		CM03 (0201)			CM05 (0402)				CM (06	105 03)					CN (08			
	Voltage (VDC)	10	10	16	25	16	25	50	6.3	10	16	25	50	100	6.3	10	16	25	50	100
101 151	100 150																			
151	220 330	A8		B2	B2															
102	470 680 1000	A8		D2				C1						B1						
152	1500 2200 3300	- F////	B0																	
103	4700 6800 10000		В3 —			C2	C2													D1 E1
153	15000 22000 33000					- 62						B2	В1						D1 E1	G1
104	47000 68000 100000					C8	C8			В3	B2	— В2 —						G2	G1	
105	220000 470000 1000000									B8	В8	D8				G3	G2 G8	G8	M3	
106	2200000 4700000 10000000 22000000								D8						M8	M8 M8	M8	M8		

Size (EIA Co		CM316 (1206)							CM32 (1210)					CM43 (1812)	
Rated Voltage (6.3	10	16	25	50	100	10	16	25	50	100	50	100	
	7000					A1	D1 F1					В1			
47	20000 20000 10000			D2	D2 F2	D1	J3			B2	B1 F1	G1	В1	D1	
106 1000	00000 00000 00000	J8	J8	J8	J8 J3	J3]		G8	G2 G8	G8			D1		

Optional Spec.

Two digits alphanumerics in capacitance chart denote dimensions and tan $\delta.\,$ Please refer to the below table for detail.

(Example)
In case of "B3" for CM03;
L: 0.6±0.03mm
W: 0.3±0.03mm
T: 0.3±0.03mm Tan δ : 5.0% max.

Size	Size	Dir	mension (m	nm)		
Size	Code	L	W	Т		
02	Α	0.4±0.02	0.2±0.02	0.2±0.02		
03	В	0.6±0.03	0.3±0.03	0.3±0.03		
05	С	1.0±0.05	0.5±0.05	0.5±0.05		
105	В	1.6±0.10	0.8±0.10	0.8±0.10		
105	D	1.6±0.15	0.8±0.15	0.8±0.15		
	D			0.6±0.10		
21	E	2.0±0.10	1.25±0.10	0.85±0.10		
21	G			1.25±0.10		
	М	2.0±0.20	1.25±0.20	1.25±0.20		
	Α			0.85±0.10		
316	D	3.2±0.20	1.6±0.15	1.15±0.10		
310	F			1.6±0.15		
	J	3.2±0.20	1.6±0.20	1.6±0.20		
	В			1.40 max.		
32	F	3.2±0.20	2.5±0.20	2.0±0.2		
	G			2.5±0.2		
43	В	4.5±0.30	3.2±0.20	2.0±0.2		
43	D	4.5±0.30	J.Z±U.ZU	2.5±0.2		

$\begin{array}{c} \text{Tan } \delta \\ \text{Code} \end{array}$	Tan δ
1	2.5% max.
2	3.5% max.
3	5.0% max.
5	7.5% max.
8	12.5% max.





Y5V Dielectric

	Size A Code)			105 ·02)			CM105 (0603)				CM21 (0805)			CM316 (1206)			CM32 (1210)		
	Voltage (VDC)	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	10	16	25
102 472	1000 2200 4700				СЗ														
103 473	10000 22000 47000		C6	C3	CS				В3										
104 474	100000 220000 470000	C8					В6	B3 B4			E6	D3 E3 G3	E3 G3						
105 475	1000000 2200000 4700000					B8				G8	G6	G4			D6	D4			
106 476	10000000 22000000 47000000									G9				F8 F9	F6		F8	C6	C6

Two digits alphanumerics in capacitance chart denote dimensions and tan $\delta. \,$ Please refer to the below table for detail.

$$\label{eq:continuous} \begin{split} & \text{(Example)} \\ & \text{In case of "C8" for CM05;} \\ & \text{L} : 1.0 \pm 0.05 \text{mm} \\ & \text{W} : 0.5 \pm 0.05 \text{mm} \\ & \text{T} : 0.5 \pm 0.05 \text{mm} \\ & \text{Tan } \delta : 12.5\% \text{ max.} \end{split}$$

;	Size	Size	Dir	Dimension (mm)								
	Size	Code	L	W	Т							
	05	С	1.0±0.05	0.5±0.05	0.5±0.05							
	105	В	1.6±0.10	0.8±0.10	0.8±0.10							
		D	2.0±0.10	1.25±0.10	0.6±0.10							
	21	Е	2.0±0.10	1.25±0.10	0.85±0.10							
		G	2.0±0.10	1.25±0.10	1.25±0.10							
	316	D	3.2±0.20	1.6±0.15	1.15±0.10							
	310	F	3.2±0.20	1.6±0.15	1.6±0.15							
	32	C	3.2±0.20	2.5±0.20	1.60 max.							
	32	F	3.2±0.20	2.5±0.20	2.0±0.2							

$\begin{array}{c} \text{Tan } \delta \\ \text{Code} \end{array}$	Tan δ
3	5.0% max.
4	7.0% max.
6	9.0% max.
8	12.5% max.
9	16.0% max.





Test Conditions and Specifications for Temperature Compensation Type (C \triangle to U \triangle • SL Characteristics) CM/ CT/ CF Series

Test	Items		Test Condition	s	Specifications				
Capacitance V	alue (C)	Capacitan	ce Frequency	Volt	Within tolerance				
Q		C≤1000p	F 1MHz±10%	0.5 to 5Vrms	C≥30pF : Q≥1000				
Insulation Res	istance (IR)	Measured after minute at rook For the rated for 1 minute at a second control of the seco	er the rated voltage m ambient. voltage of over 630\ tt room ambient. nd discharge current	V, apply 500V	C<30pF : Q≥400+20C				
Dielectric Res	istance	Apply 1.5 times Apply 1.2 times	of the rated voltage for s when the rated voltage s when the rated voltage and discharge current ared 50mA.	ge is 250V or over. ge is 630V or over.	No problem observed				
Appearance		Microscope (10× magnification)		No problem observed				
Termination St	rength		vard force of 500g (5 ple. Apply 2N for 02	,	No problem observed				
Bending Stren	gth	Glass epoxy F time 10 secon	CB: Fulcrum spacing ds.	g: 90mm, duration	No significant damage at 1mm bent				
Vibration	Appearance		uency: 10 to 55 (Hz)		No problem observed				
Test	ΔC	Amplitude: 1. Sweeping cor	5mm ndition: 10→55→10ŀ	Hz/ 1 minute in X.	Within Tolerance				
	Q	Y and Z	hours each, 6 hours		C≥30pF : Q≥1000 C<30pF : Q≥400+20C				
Soldering	Appearance		ple in 260°C±5°C so		No problem observed				
Heat Resistance	ΔC	seconds and after 24±2 ho	place in room ambie urs.	ent, and measure	Within ±2.5% or ±0.25pF, whichever is larger				
	Q	(Pre-heating	conditions)		C≥30pF: Q≥1000				
	IR .	Order	Temperature 80 to 100°C	7 Time 2 minutes	C<30pF: Q≥400+20C				
	Withstanding Voltage	_	150 to 200°C nd discharge current eed 50mA for IR and	2 minutes tof the capacitor	Over 10000MΩ or 500MΩ • μF whichever is less Resist without problem				
Solderablity		Sneaking cond Snea Sold Sn-3Ag-0	ler 235±5°C	2±0.5 sec. 3±0.5 sec.	Solder coverage : 90% min.				
Temperature	Appearance	(Cycle)			No problem observed				
Cycle	ΔC	Room temper	rature (3min.)→		Within ±2.5% or ±0.25pF, whichever is larger				
	Q	Lowest opera Room temper	tion temperature (30 rature (3min.)→		C≥30pF : Q≥1000 C<30pF : Q≥400+20C				
	IR	Highest opera	ation temperature(30	Jmin.)	Over 10000M Ω or 500M Ω • μ F, whichever is less				
	Withstanding Voltage After 5 cycles, measure after 24±2 hours. The charge and discharge current of the capacitor must not exceed 50mA for IR and withstanding voltage measurement.				Resist without problem				
Load	Appearance	After applying	rated voltage for 50	00+12/ -0 hours	No problem observed				
Humidity Test			on at 40°C±2°C, hur v parts to stabilize fo	•	Within ±7.5% or ±0.75pF, whichever is larger				
(Except CF Series)	Q	room tempera	ature before measure and discharge current	ement.	C≥30pF: Q≥200 C<30pF: Q≥100+10C/3				
	IR	must not exce	eed 50mA for IR me	asurement.	Over $500M\Omega$ or $25M\Omega \cdot \mu F$, whichever is less				
High-	Appearance	After applying	twice the rated vol	tage at the	No problem observed.				
Temperature with Loading	ΔC		of 125±3°C for 1000		Within ±3% or ±0.3pF, whichever is larger				
Eodding	Q	Apply 1.5 times Apply 1.2 times	sample after 24±2 he s when the rated voltage s when the rated voltage and discharge current	ge is 250V or over. ge is 630V or over.	C≥30pF: Q≥350 10pF <c<30pf: 2<br="" q≥275+5c="">C<10pF: Q≥200+10C</c<30pf:>				
	IR	_	eed 50mA for IR me		Over 1000M Ω or 50M Ω • μ F, whichever is less				
			ed range in previous	abaut					

Please ask for individual specification for the hatched range in previous chart.



Test Conditions and Specifications for High Dielectric Type (X5R, X7R) CM/ CT/ CA Series

Test	Items	Т	est Condition	ıs	Specifications				
Capacitance V	/alue (C)	Measure after hea	at treatment		Within tolerance				
Tanδ (%)		Capacitance C≤10μF C>10μF	1kHz±10%	Volt 1.0±0.2Vrms 0.5±0.2Vrms	Refer to capacitance chart				
Insulation Res	sistance (IR)	Measured after the minute at room an The charge and di must not exceed 5	nbient. scharge current 50mA.	of the capacitor	Over 10000M Ω or 500M Ω • μ F, whichever is less				
Dielectric Res	istance	Apply 2.5 times of the charge and of must not exceed	ischarge currer	for 1 to 5 seconds. nt of the capacitor	No problem observed				
Appearance		Microscope (10×			No problem observed				
Termination S	trength	Apply a sideward force note: 2N for 020 Exclude CT series	1 size in for 010	05 size.	No problem observed				
Bending Strength		time 10 seconds. Exclude CT series	with thickness of		No significant damage at 1mm bent				
Vibration	Appearance	Take the initial va			No problem observed				
Test	ΔC	Vibration frequent Amplitude: 1.5mr		(-)	Within tolerance				
	Tanδ (%)	Sweeping condition: 1 Directions: 2 hour	$0\rightarrow55\rightarrow10$ Hz/1 m ² s each, 6 hours	s total.	Within tolerance				
Soldering	Appearance	Take the initial va		eatment. solder for 10±0.5	No problem observed				
Heat AC				ient, and measure	Within ±7.5%				
ricoiotarice	Tanδ (%)	after 24±2 hours.		,	Within tolerance				
	IR	(Pre-heating cond			Over $10000 \mathrm{M}\Omega$ or $500 \mathrm{M}\Omega$ • $\mu\mathrm{F}$, whichever is less				
	Withstanding Voltage	1 2 1		2 minutes 2 minutes 2 minutes e capacitor must not	Resist without problem				
Solderablity		Soaking condition Sn63 Solder Sn-3Ag-0.5Co	235±5°C 245±5°C	2±0.5 sec. 3±0.5 sec.	Solder coverage : 90% min.				
Temperature	Appearance	Take the initial va (Cycle)	lue after heat tr	eatment.	No problem observed				
Cycle	ΔC	Room temperatu	re (3min.)→		Within ±7.5%				
	Tanδ (%)	Lowest operation		0min.)→	Within tolerance				
	Withstanding Voltage	Room temperatur Highest operation After 5 cycles, me The charge and disch exceed 50mA for IR a	n temperature(3 easure after 24± narge current of the	±2 hours. e capacitor must not	Over 10000MΩ or 500MΩ • μF, whichever is less Resist without problem				
Load	Appearance	Take the initial va			No problem observed				
Humidity	ΔC	After applying rat in pre-condition a	ed voltage for 5	500+12/ –0 hours	Within ±12.5%				
Test	Tanδ (%)	95%RH. allow ba	แ 40 C±∠ C, ที่บ rts to stabilize f	for 24±2 hours, at	200% max. of initial value				
	room temperature before measurement. The charge and discharge current of the capacitor must not exceed 50mA for IR measurement.			Over 500M Ω or 25M Ω • μ F, whichever is less					
High-	ligh- Appearance Take the initial value after voltage treatment.			No problem observed					
Temperature with	ΔC	After applying twice operation temperation			Within ±12.5%				
Loading	Tanδ (%)	measure the same			200% max. of initial value				
Loading	IR		lischarge currer 50mA for IR me he rated voltage is 1	nt of the capacitor easurement. 0V or less. Applied	Over 1000M Ω or 50M Ω • μ F, whichever is less				

Pre-	Heat	Keep specimen at 150+0/ −10°C for 1 hour, leave specimen at room ambient for 24±2 hours.
treatment	Voltage	Apply the same test condition for 1 hour, then leave the specimen at room ambient for 24±2 hours.

High-temperature with Loading Applied Voltage (Rated Voltage × □)

Applied Voltage	Rated Voltage	Products
	4V	CT03X5R104
×1.3	6.3V	CM105X5R475, CM316X5R476
	0.30	CT05X5R104, CT21X5R106, CT03X5R104
	16V	CM105X7R474-105, CM21X7R105-475, CM316X7R475-106, CM32X7R106-226, CM05X5R224, CM105X5R225, CM21X5R475-106, CM316X5R226
	100	CT105X5R105, CT21X5R225-475, CT316X5R106
	25V	CM105X7R474, CM21X7R105-225, CM316X7R475, CM32X7R106, CM105X5R474-105, CM21X5R225-106, CM316X5R106, CM32X5R106-226
×1.5	250	CT316X5R225-106
	50V	CM21X5R105
	500	CT21X5R225, CT316X5R105-475
	100V	CM32X7RK74, CM43X7R105

Please ask for individual specification for the hatched range in previous chart.





Test Conditions and Specifications for High Dielectric Type (Y5V) CM/ CT/ CA Series

Test	Items		Test C	conditions		Specifications				
Capacitance V	/alue (C)	Measure afte	r heat trea	tment		Within tolerance				
Tan δ (%)			uency ±10%		Volt 0.2Vrms	Refer to capacitance chart				
Insulation Res	istance (IR)	Measured after minute at room			oplied for 1	Over 10000M Ω or 500M Ω • μ F, whichever is less				
Dielectric Res	istance		nd dischar	rge current c	1 to 5 seconds. of the capacitor	No problem observed				
Appearance		Microscope (10× magn	ification)		No problem observed				
Termination S	trength	mounted san	nple.		(5N) to a PCB- s than 0.66mm.	No problem observed				
Bending Stren	gth	time 10 seco	nds.		90mm, durations than 0.66mm.	No significant damage at 1mm bent				
Vibration	Appearance	Take the initia			ment.	No problem observed				
Test	ΔC	Vibration fred Amplitude: 1.		to 55 (Hz)		Within tolerance				
	Tan δ (%)	Sweeping co Y and Z Directions: 2			z/ 1 minute in X otal.	Within tolerance				
Soldering	Appearance	Take the initia				No problem observed				
Heat Resistance	ΔC		•		older for 10±0.5 nt, and measure	Within ±20%				
	Tanδ (%)	after 24±2 ho		N		Within tolerance				
	IR	(Pre-heating Order		tions) emperature Time		Over 10000M Ω or 500M Ω • μ F, whichever is less				
	Withstanding Voltage		150 to and discha ceed 50m	•	2 minutes 2 minutes of the capacitor d withstanding					
Solderablity		Soaking condition Sn63 Solder 235±5°C 2±			2±0.5 sec. 3±0.5 sec.	Solder coverage : 90% min.				
Temperature	Appearance	Take the initia	al value aft	er heat treat	ment.	No problem observed				
Cycle	ΔC	(Cycle) Room tempe	rature (3m	in.)→		Within ±20%				
	Tanδ (%)	Lowest opera		,	nin.)→	Within tolerance				
	IR	Room tempe Highest oper			nin.)	Over 10000M Ω or 500M Ω • μ F, whichever is less				
	Withstanding Voltage	After 5 cycles The charge a must not exc voltage meas	nd dischar eed 50mA	rge current c	of the capacitor	Resist without problem				
Load	Appearance	Take the initia		•		No problem observed				
Humidity Test	ΔC	in pre-condit			+12/ -0 hours dity 90 to	Within ±30%				
	Tanδ (%)				24±2 hours, at	150% max. of initial value				
	room temperature before measurement. The charge and discharge current of the capacitor must not exceed 50mA for IR measurement.				of the capacitor	Over 500M Ω or 25M Ω • μ F, whichever is less				
High-	Appearance	After applying twice the rated voltage at the highest operation temperature for 1000+12/-0 hours, measure the sample after 24±2 hours. The charge and discharge current of the capacitor				No problem observed				
Temperature with	ΔC					Within ±30%				
Loading	Tanδ (%)				s.	150% max. of initial value				
	IR					Over $1000M\Omega$ or $50M\Omega \cdot \mu F$, whichever is less				
Due	Hoot					<u> </u>				
Pre- treatment	Heat Voltage					, leave specimen at room ambient for 24±2 hours. nen leave the specimen at room ambient for 24±2 hours.				
doddinont	Voltage	Apply life	same tes	i condition	i ioi i lioui, li	ion loave the specimen at room ambient for 24±2 nours.				



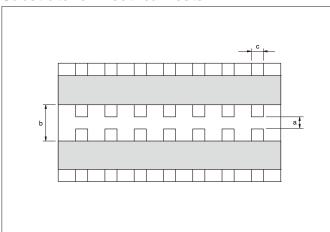


Test Conditions and Specifications for High Dielectric Type (X7R) CF Series

Test Items		Test Conditions	Specifications	
Capacitance Value (C)		Measure after heat treatment	Within tolerance	
Tanδ (%)		CapacitanceFrequencyVoltC≤10μF1kHz±10%1.0±0.2Vrms	Within ±2.5%	
Insulation Resistance (IR)		Measured after the rated voltage is applied for 1 minute at room ambient. Measured after the 500V is applied for 1 minute at room ambient for the rated voltage over 630V. The charge and discharge current of the capacitor must not exceed 50mA.	Over 10000MΩ or 500MΩ • μF, whichever is less Over 100MΩ • μF for CF316X7R104/ 250V and CF43X7R474/ 250V CF55X7R105/ 250V and CF55X7R224/ 630V	
Dielectric Resistance		Apply 1.5 times when the rated voltage is 250V or over, apply 1.2 times when the rated voltage is 630V or over for 1 to 5 seconds. The charge and discharge current of the capacitor must not exceed 50mA.	No problem observed	
Appearance		Microscope (10× magnification)	No problem observed	
Termination S	trength	Apply a sideward force of 500g (5N) to a PCB-mounted sample.	No problem observed	
Bending Stren	gth	Glass epoxy PCB: Fulcrum spacing: 90mm, duration time 10 seconds.	No significant damage at 1mm bent	
Vibration	Appearance	Take the initial value after heat treatment. Vibration frequency: 10 to 55 (Hz)	No problem observed	
Test	ΔC	Amplitude: 1.5mm	Within tolerance	
	Tanδ (%)	Sweeping condition: 10→55→10Hz/ 1 minute in X, Y and Z Directions: 2 hours each, 6 hours total.	Within tolerance	
Soldering Appearance		Take the initial value after heat treatment.	No problem observed	
Heat Resistance	ΔC	Soak the sample in 260°C±5°C solder for 10±0.5 seconds and place in room ambient,	Within ±7.5%	
	Tanδ (%)	and measure after 24±2 hours. (Pre-heating conditions)	Within tolerance	
	IR	Order Temperature Time 1 80 to 100°C 2 minutes 2 150 to 200°C 2 minutes	Over 10000M Ω or 500M Ω • μ F, whichever is less Over 100M Ω • μ F for CF316X7R104/ 250V and CF43X7R474/ 250V CF55X7R105/ 250V and CF55X7R224/ 630V	
	Withstanding Voltage	The charge and discharge current of the capacitor must not exceed 50mA for IR and withstanding voltage measurement.	Resist without problem	
Solderablity		Soaking condition Sn63 Solder 235±5°C 2±0.5 sec. Sn-3Ag-0.5Cu 245±5°C 3±0.5 sec.	Solder coverage : 90% min.	
Temperature	Appearance	Take the initial value after heat treatment.	No problem observed	
Cycle	ΔC	(Cycle) Room temperature (3min.)→	Within ±7.5%	
	Tanδ (%)	Lowest operation temperature (30min.)→	Within tolerance	
	IR	Room temperature (3min.)→ Highest operation temperature(30min.) After 5 cycles, measure after 24±2 hours. The charge and discharge current of the	Over 10000MΩ or 500MΩ • μF, whichever is less Over 100MΩ • μF for CF316X7R104/ 250V and CF43X7R474/ 250V CF55X7R105/ 250V and CF55X7R224/ 630V	
	Withstanding Voltage	capacitor must not exceed 50mA for IR and withstanding voltage measurement.	Resist without problem	
High-	Appearance	Take the initial value after voltage treatment.	No problem observed	
Temperature with	ΔC	After applying specified voltage at the highest operation temperature for 1000+12/ -0 hours,	Within ±12.5%	
Loading	Tanδ (%)	then measure the sample after 24±2 hours. The applied voltage shall be;	200% max. of initial value	
	IR 1.5 times the rated voltage when the rated voltage is 250V or over. 1.2 times when the rated voltage is 630V or over. The charge and discharge current of the capacitor must not exceed 50mA for IR measurement.		Over 1000M Ω or 50M Ω • μ F, whichever is less	
Pre-	Heat	Keep specimen at 150+0/ −10°C for 1 hour.	leave specimen at room ambient for 24±2 hours.	
treatment	Voltage		en leave the specimen at room ambient for 24±2 hours.	



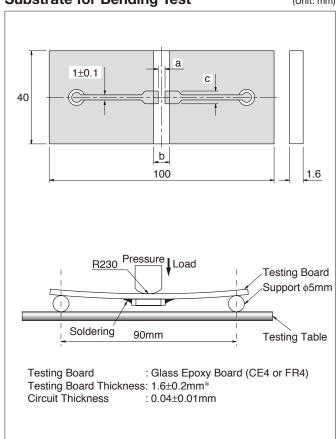
Substrate for Electrical Tests



			(Unit: mm)
Size (EIA Code)	а	b	С
02 (01005)	0.15	0.50	0.20
03 (0201)	0.26	0.92	0.32
05 (0402)	0.4	1.4	0.5
105 (0603)	1.0	3.0	1.2
21 (0805)	1.2	4.0	1.65
316 (1206)	2.2	5.0	2.0
32 (1210)	2.2	5.0	2.9
42 (1808)	3.5	7.0	3.7
43 (1812)	3.5	7.0	3.7
52 (2208)	4.5	8.0	5.6
55 (2220)	4.5	8.0	5.6

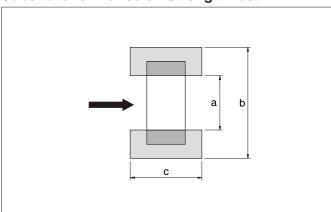
Substrate for Bending Test





* 02, 03, 05 and array: 0.8±0.1mm

Substrate for Adhesion Strength Test



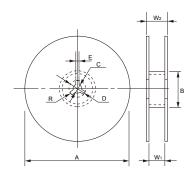


Multilayer Ceramic Chip Capacitors Packaging Options

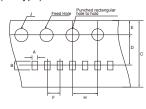


Tape and Reel

• Reel

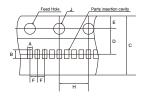


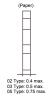
F=1mm (02 Type)



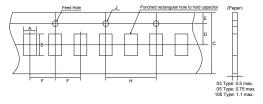


F=1mm (02, 03, 05 Type)

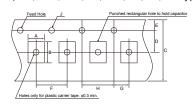


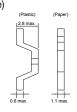


F=2mm (03, 05, 105 Type)

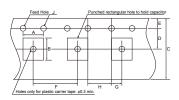


F=4mm (105, D11, F12, 21, 316, 32, 42, 52 Type)





F=8mm (43, 55 Type)





Reel

(Unit: mm)

Code Reel	Α	В	С	D
7-inch Reel (CODE: T, H, Q, P)	180 +0 -2.0	φ60 min.	13±0.5	21±0.8
13-inch Reel (CODE: L, N)	330±2.0	φ100±1.0	13±0.5	21±0.6
Code	_			_
Reel	E	W 1	W 2	R
Reel 7-inch Reel (CODE: T, H, Q)	2.0±0.5	W ₁ 10.0±1.5	W ₂	1.0

^{*} Carrier tape width 8mm.

Carrier Tape

(Unit: mm)

Size (EIA Code)	Α	В	F
02 (01005)	0.23±0.02	0.43±0.02	1.0±0.02
02 (01005)	0.25±0.03	0.45±0.03	2.0±0.05
03 (0201)*	0.37±0.03	0.67±0.03	1.0±0.05
03 (0201)	0.37±0.03	0.07±0.03	2.0±0.05
05 (0402)	0.65±0.1	1.15±0.1	1.0±0.05
05 (0402)	0.65±0.1	1.15±0.1	2.0±0.05
105 (0603)	1.0±0.2	1.8±0.2	4.0±0.1
21 (0805)	1.5±0.2	2.3±0.2	4.0±0.1
316 (1206)	2.0±0.2	3.6±0.2	4.0±0.1
32 (1210)	2.9±0.2	3.6±0.2	4.0±0.1
42 (1808)	2.4±0.2	4.9±0.2	4.0±0.1
43 (1812)	3.6±0.2	4.9±0.2	8.0±0.1
52 (2208)	2.4±0.2	6.0±0.2	4.0±0.1
55 (2220)	5.3±0.2	6.0±0.2	8.0±0.1
D11 (0405)	1.15±0.2	1.55±0.2	4.0±0.1
F12 (0508)	1.5±0.2	2.3±0.2	4.0±0.1

^{*} Option : A : 0.39±0.03, B : 0.69±0.03

(Unit: mm)

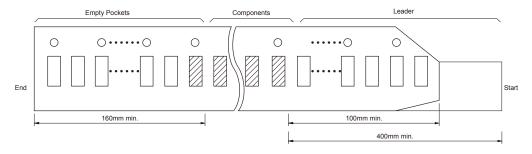
	,						
F	Carrier Tape	С	D	E	G	Н	J
1.0 ±0.02	4mm Plastic	4.0 +0.05	1.8 ±0.02	0.9 ±0.05	_	2.0 ±0.04	0.8 ±0.02
1.0 ±0.05	1mm Paper	8.0 +0.3/ -0.1				4.0 ±0.05	
2.0 ±0.05	8mm Paper	8.0 ±0.3	3.5 ±0.05	1.75	2.0		1.5
4.0 ±0.1	8mm Plastic			±0.1	±0.05	4.0 ±0.1	+0.1/ -0
8.0 ±0.1	12mm Plastic	12.0 ±0.3	5.5 ±0.05				

For size 42 (1808) or over, Tape width 12mm and W1: 14 ± 1.5 , W2: 18.4mm max.





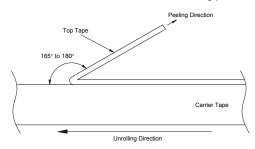
Detail of leader and trailer

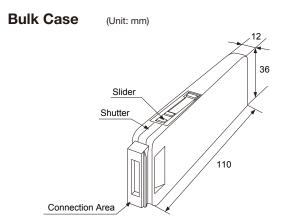


Adhesive tape

- 1) The exfoliative strength when peeling off the top tape from the carrier tape by the method of the following figure shall be $^{*}0.1$ to 0.7N. *02 Size: 0.1 to 0.5N
- 2) When the top tape is peeled off, the adhesive stays on the top tape.
- 3) Chip capacitors will be in a state free without being stuck on the thermal adhesive tape.

Exfoliating angle: 165 to 180 degrees to the carrier tape. Exfoliating speed: 300 mm/min.





• Please contact Kyocera for details.



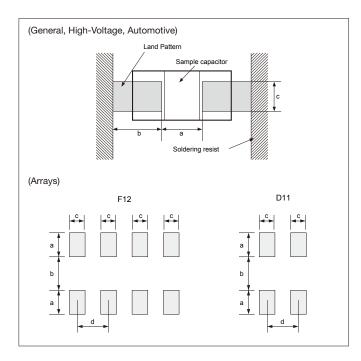
Multilayer Ceramic Chip Capacitors Surface Mounting Information



Dimensions for recommended typical land

Since the amount of solder (size of fillet) to be used has direct influence on the capacitor after mounting, the sufficient consideration is necessary.

When the amounts of solder is too much, the stress that a capacitor receives becomes larger. It may become the cause of a crack in the capacitor. When the land design of printed wiring board is considered, it is necessary to set up the form and size of land pattern so that the amount of solder is suitable.



Design of printed circuit and Soldering

The recommended fillet height shall be 1/2 to 1/3 of the thickness of capacitors. When mounting two or more capacitors in the common land, it is necessary to separate the land with the solder resist strike so that it may become the exclusive land of each capacitor.

General, High-Voltage

(Unit: mm)

Size (EIA Code)	L×W	а	b	С
02 (01005)	0.4×0.2	0.13 to 0.20	0.12 to 0.18	0.20 to 0.23
03 (0201)	0.6×0.3	0.20 to 0.30	0.25 to 0.35	0.30 to 0.40
05 (0402)	1.0×0.5	0.30 to 0.50	0.35 to 0.45	0.40 to 0.60
105 (0603)	1.6×0.8	0.70 to 1.00	0.80 to 1.00	0.60 to 0.80
21 (0805)	2.0×1.25	1.00 to 1.30	1.00 to 1.20	0.80 to 1.10
316 (1206)	3.2×1.6	2.10 to 2.50	1.10 to 1.30	1.00 to 1.30
32 (1210)	3.2×2.5	2.10 to 2.50	1.10 to 1.30	1.90 to 2.30
42 (1808)	4.5×2.0	2.50 to 3.20	1.80 to 2.30	1.50 to 1.80
43 (1812)	4.5×3.2	2.50 to 3.20	1.80 to 2.30	2.60 to 3.00
52 (2208)	5.7×2.0	4.20 to 4.70	2.00 to 2.50	1.50 to 1.80
55 (2220)	5.7×5.0	4.20 to 4.70	2.00 to 2.50	4.20 to 4.70

Automotive

(Unit: mm)

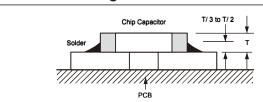
Size (EIA Code)	L×W	а	b	С
105 (0603)	1.6×0.8	0.60 to 0.90	0.80 to 1.00	0.70 to 1.00
21 (0805)	2.0×1.25	0.90 to 1.20	0.80 to 1.20	0.90 to 1.40
316 (1206)	3.2×1.6	1.40 to 1.90	1.00 to 1.30	1.30 to 1.80

Arrays

(Unit: mm)

	а	b	С	d
F12 (0508)	0.5	0.5	0.3	0.5
D11 (0405)	0.69	0.28	0.3	0.64

Ideal Solder Height



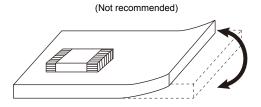
Item	Not recommended example	Recommended example/ Separated by solder
Multiple parts mount		Solder resist
Mount with leaded parts	Leaded parts	Solder resist Leaded parts
Wire soldering after mounting	Soldering iron Wire	Solder resist
Overview	Solder resist	Solder resist

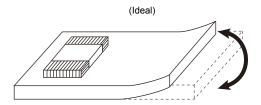


Mounting Design

The chip could crack if the PCB warps during processing after the chip has been soldered.

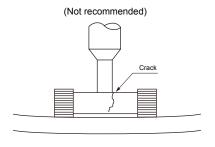
Recommended chip position on PCB to minimize stress from PCB warpage

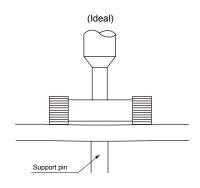




Actual Mounting

- 1) If the position of the vacuum nozzle is too low, a large force may be applied to the chip capacitor during mounting, resulting in cracking.
- 2) During mounting, set the nozzle pressure to a static load of 100 to 300 gf.
- 3) To minimize the shock of the vaccum nozzle, provide a support pin on the back of the PCB to minimize PCB flexture.





- 4) Bottom position of pick up nozzle should be adjusted to the top surface of a substrate which camber is corrected.
- 5) To reduce the possibility of chipping and cracks, minimize vibration to chips stored in a bulk case.
- 6) The discharge pressure must be adjusted to the part size. Verify the pressure during setup to avoid fracturing or cracking the chips capacitors.

Resin Mold

- 1) If a large amount of resin is used for molding the chip, cracks may occur due to contraction stress during curing. To avoid such cracks, use a low shrinkage resin.
- 2) The insulation resistance of the chip will degrade due to moisture absorption. Use a low moisture absorption resin.
- 3) Check carefully that the resin does not generate a decomposition gas or reaction gas during the curing process or during normal storage. Such gases may crack the chip capacitor or damage the device itself.



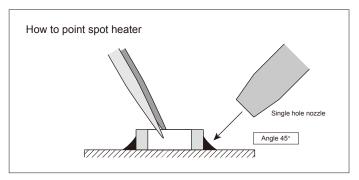
Multilayer Ceramic Chip Capacitors Surface Mounting Information



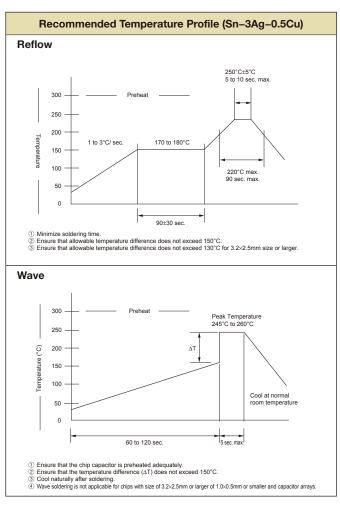
Soldering Method

- 1) Ceramic is easily damaged by rapid heating or cooling. If some heat shock is unavoidable, preheat enough to limit the temperature difference (Delta T) to within 130 degree Celsius.
- 2) The product size 1.6×0.8mm to 3.2×1.6mm can be used in reflow and wave soldering, and the product size of bigger than 3.2×1.6mm, or smaller than 1.6×0.8mm, and capacitor arrays can be used in reflow.
 - Circuit shortage and smoking can be created by using capacitors which are used neglecting the above caution.
- 3) Please see our recommended soldering conditions.
- 4) In case of using Sn-Zn Solder, please contact us in advance.
- 5) The following condition is recommended for spot heater application.
- · Recommended spot heater condition

Item	Condition
Distance	5mm min.
Angle	45°
Projection Temp.	400°C max.
Flow rate	Set at the minimum
Nozzle diameter	2φ to 4φ (Single hole type)
Application time	10 sec. max. (1206 and smaller) 30 sec.max. (1210 and larger)



Recommended Temperature Profile (62Sn Solder) Reflow Peak temperature 230°C±5°C 15 seconds maximum 300 Cool at normal room 250 temperature after removing from ΔΤ 200 More than 180°C, 50 0 60 seconds 60 seconds Minimize soldering time. Ensure that the temperature difference (ΔT) does not exceed 150°C. Ensure that the temperature difference (ΔT) does not exceed 130°C for 3.2×2.5mm size or large! MLCC can withstand the above reflow conditions up to 3 times. Wave 300 Peak Temperature 230°C to 260°C 250 ΔΤ ŝ 200 100 Cool at normal room temperature 50 60 to 120 sec.



Soldering iron

1) Temperature of iron chip 1206 and smaller 350°C max. 5) Cautions

Cool naturally after soldering.
 Wave soldering is not applicable for chips with size of 3.2×2.5mm or larger of 1.0×0.5mm or smaller and capacitor arrays

1210 and larger 280°C max.

80W max. 2) Wattage

3) Tip shape of soldering iron

Ensure that the chip capacitor is preheated adequately.
 Ensure that the temperature difference (ΔT) does not exceed 150°C.

4) Soldering Time

\$3.0mm max. 3 sec. max.

a) Pre-heating is necessary rapid heating must be avoided.

Delta T≤150°C

- b) Avoid direct touching to capacitors.
- c) Avoid rapid cooling after soldering. Natural cooling is recommended.
- *Consult as if it is difficult to keep the temperature 280°C max. for 1210 and larger MLCC'S.





Circuit Design

- 1. Once application and assembly environments have been checked, the capacitor may be used in conformance with the rating and performance which are provided in both the catalog and the specifications. Use exceeding that which is specified may result in inferior performance or cause a short, open, smoking, or flaming to occur, etc.
- 2. Please consult the manufacturer in advance when the capacitor is used in devices such as: devices which deal with human life, i.e. medical devices; devices which are highly public orientated; and devices which demand a high standard of liability.
 Accident or malfunction of devices such as medical devices, space equipment and devices having to do with atomic power could generate grave consequence with respect to human lives or, possibly, a portion of the public. Capacitors used in these devices may require high reliability design different from that of general purpose capacitors.
- 3. Please use the capacitors in conformance with the operating temperature provided in both the catalog and the specifications.

 Be especially cautious not to exceed the maximum temperature. In the situation the maximum temperature set forth in both the catalog and specifications is exceeded, the capacitor's insulation resistance may deteriorate, power may suddenly surge and short-circuit may occur.

 The capacitor has a loss, and may self-heat due to equivalent series resistance when alternating electric current is passed therethrough. As this effect becomes especially pronounced in high frequency circuits, please exercise caution.

 When using the capacitor in a (self-heating) circuit, please make sure the surface of the capacitor remains under the maximum temperature for usage. Also, please make certain temperature rises remain below 20°C.
- 4. Please keep voltage under the rated voltage which is applied to the capacitor. Also, please make certain the peak voltage remains below the rated voltage when AC voltage is super-imposed to the DC voltage.
 In the situation where AC or pulse voltage is employed, ensure average peak voltage does not exceed the rated voltage.
 Exceeding the rated voltage provided in both catalog and specifications may lead to defective withstanding voltage or, in worst case situations, may cause the capacitor to smoke or flame.
- 5. When the capacitor is to be employed in a circuit in which there is continuous application of a high frequency voltage or a steep pulse voltage, even though it is within the rated voltage, please inquire to the manufacturer.
 In the situation the capacitor is to be employed using a high frequency AC voltage or a extremely fast rising pulse voltage, even though it is within the rated voltage, it is possible capacitor reliability will deteriorate.
- 6. It is a common phenomenon of high-dielectric products to have a deteriorated amount of static electricity due to the application of DC voltage.

 Due caution is necessary as the degree of deterioration varies depending on the quality of capacitor materials, capacity, as well as the load voltage at the time of operation.
- 7. Do not use the capacitor in an environment where it might easily exceed the respective provisions concerning shock and vibration specified in the catalog and specifications.
 In addition, it is a common piezo phenomenon of high dielectric products to have some voltage due to vibration or to have noise due to voltage change. Please contact sales in such case.
- 8. If the electrostatic capacity value of the delivered capacitor is within the specified tolerance, please consider this when designing the respective product in order that the assembled product function appropriately.
- 9. Please contact us upon using conductive adhesives.

Storage

- 1. If the component is stored in minimal packaging (a heat–sealed or chuck–type plastic bag), the bag should be kept closed. Once the bag has been opened, reseal it or store it in a desiccator.
- 2. Keep storage place temperature +5 to +40 degree C, humidity 20 to 70% RH.
- 3. The storage atmosphere must be free of gas containing sulfur and chlorine. Also, avoid exposing the product to saline moisture. If the product is exposed to such atmospheres, the terminals will oxidize and solderability will be effected.
- 4. Precautions 1) to 3) apply to chip capacitors packaged in carrier tapes and bulk cases.
- 5. The solderability is assured for 12 months from our shipping date (six months for silver palladium) if the above storage precautions are followed.
- $6. \ Chip\ capacitors\ may\ crack\ if\ exposed\ to\ hydrogen\ (H_2)\ gas\ while\ sealed\ or\ if\ coated\ with\ silicon,\ which\ generates\ hydrogen\ gas.$

Safety application guideline and detailed information of electrical properties are also provided in Kyocera home page; URL: http://www.kyocera.co.jp/electronic/